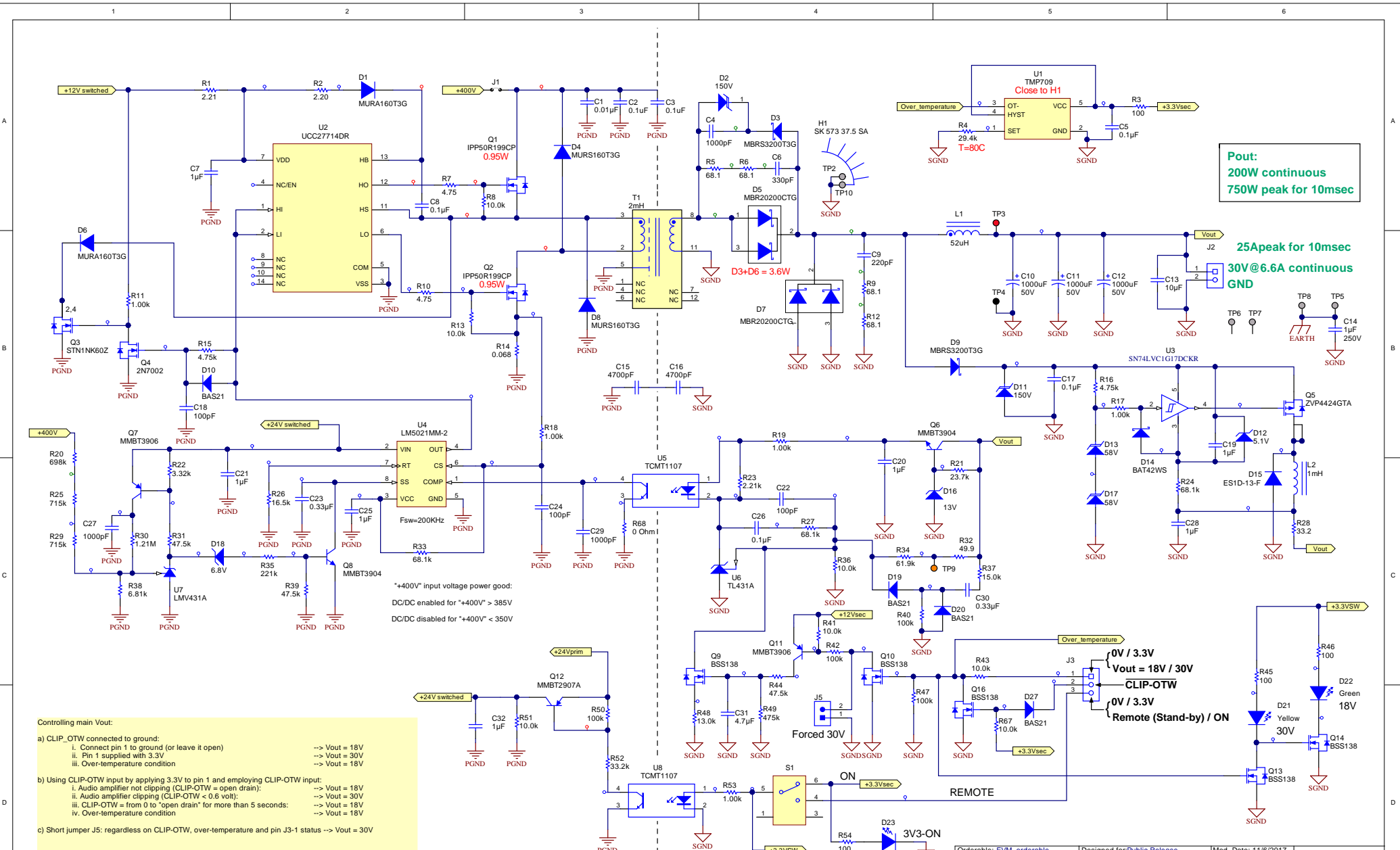


Assembly Notes:
 Built on PMP30183 Rev_A PCB

Pout:
 200W continuous
 750W peak for 10msec



Pout:
200W continuous
750W peak for 10msec

25Apeak for 10msec
30V@6.6A continuous
GND

+400V input voltage power good:
DC/DC enabled for "+400V" > 385V
DC/DC disabled for "+400V" < 350V

Controlling main Vout:

a) CLIP_OTW connected to ground:
 i. Connect pin 1 to ground (or leave it open) --> Vout = 18V
 ii. Pin 1 supplied with 3.3V --> Vout = 30V
 iii. Over-temperature condition --> Vout = 18V

b) Using CLIP_OTW input by applying 3.3V to pin 1 and employing CLIP_OTW input:
 i. Audio amplifier not clipping (CLIP_OTW = open drain): --> Vout = 18V
 ii. Audio amplifier clipping (CLIP_OTW < 0.6 volt): --> Vout = 30V
 iii. CLIP_OTW = from 0 to "open drain" for more than 5 seconds: --> Vout = 18V
 iv. Over-temperature condition --> Vout = 18V

c) Short jumper J5: regardless on CLIP_OTW, over-temperature and pin J3-1 status --> Vout = 30V

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